

L Number	Hits	Search Text	DB	Time stamp
1	5291	257/666	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/05 17:13
2	951	257/667	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/05 17:21
3	2334	257/668	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/05 17:40
4	1063	257/324	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/05 17:51
5	842	257/635	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/05 17:58
6	4668	257/758	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/05 18:31
7	2650	257/700	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/05 18:55
8	2132	438/118	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/05 19:12
9	1646	438/123	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/05 19:14
-	105	'van der waal' and 257/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/26 13:23
-	225	'van der waal' and 438/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/05 16:35
-	42	latex and 257/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/25 18:10
-	53	latex and 438/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/11 10:23
-	156	self-vulcanizing latex and (copper adj layer) and interconnect and 257/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/26 11:25

-	4063	257/666	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/09 11:04
-	644	interconnect and (multichip module) and (copper layer) and polyimide and 257/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/09 11:06
-	36	interconnect and (multichip adj module) and (copper adj layer) and polyimide and 257/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/09 14:20
-	379	257/75\$.ccls. and polymer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/11 10:24
-	233	257/75\$.ccls. and polymer and interconnect	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/11 10:25
-	10	(dielectric) and (silicon adj based adj adhesive)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/12 09:28
-	74	438/\$.ccls. and (latex)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/26 08:06
-	21	257/\$.ccls. and (polymer WITH latex)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/27 15:25
-	28	438/\$.ccls. and (polymer WITH latex)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/29 08:56
-	15	257/\$.ccls. and (adhesive WITH latex)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/28 17:08
-	40	438/\$.ccls. and (latex with particle)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/28 18:11
-	86	438/\$.ccls. and (dielectric near3 rough)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/29 08:57
-	98	257/\$.ccls. and (dielectric near3 rough)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/29 09:10